innodisk

2.5" SATA SSD 3MG2-P AES Function

Customer:
Customer
Part
Number:
Innodisk
Part
Number:
Innodisk
Model Name:
Date:

Innodisk	Customer
Approver	Approver

Total Solution For Industrial Flash Storage

Table of contents

1. PRODUCT OVERVIEW
1.1 INTRODUCTION OF INNODISK 2.5" SATA SSD 3MG2-P WITH AES FUNCTION
1.2 Product View and Models
1.3 SATA INTERFACE
1.4 2.5-inch Form Factor
2. PRODUCT SPECIFICATIONS
2.1 CAPACITY AND DEVICE PARAMETERS
2.2 Performance
2.3 ELECTRICAL SPECIFICATIONS 10
2.3.1 Power Requirement 10
2.3.2 Power Consumption10
2.4 ENVIRONMENTAL SPECIFICATIONS11
2.4.1 Temperature Ranges 11
2.4.2 Humidity
2.4.3 Shock and Vibration11
2.4.4 Mean Time between Failures (MTBF)11
2.5 CE AND FCC COMPATIBILITY 12
2.6 RoHS Compliance
2.7 RELIABILITY 12
2.8 TRANSFER MODE
2.9 PIN ASSIGNMENT 12
2.10 MECHANICAL DIMENSIONS 14
2.11 ASSEMBLY WEIGHT 15
2.12 Seek Time 15
2.13 Hot Plug
2.14 NAND FLASH MEMORY15
3. THEORY OF OPERATION
3.1 Overview
3.2 SATA III CONTROLLER 16
3.3 Error Detection and Correction 17
3.4 WEAR-LEVELING
3.5 BAD BLOCKS MANAGEMENT 17
3.6 IDATA GUARD
3.7 GARBAGE COLLECTION/TRIM
3.8 ICELL TECHNOLOGY (OPTIONAL) 18
3.9 QERASER FUNCTION (OPTIONAL)
3.10 2.5" SATA SSD 3MG2-P AES FUNCTION FLOW CHART

4. INSTALLATION REQUIREMENTS	
4.1 2.5" SATA SSD 3MG2-P PIN DIRECTIONS	22
4.2 ELECTRICAL CONNECTIONS FOR 2.5" SATA SSD 3MG2-P	22
4.3 Form Factor	22
4.4 DEVICE DRIVE	23
5. SMART FEATURE SET	
6. AES ALGORITHM CERTIFICATION	26
7. PART NUMBER RULE	

REVISION HISTORY

Revision	Description	Date
Preliminary	First Released	Sep, 2015
Rev 1.0	Update part number rule	Oct, 2015
Rev 1.1	Update Capacity and part number rule	Nov, 2015
Rev 1.2	Add Toshiba 15nm information	Jun., 2016
Rev 1.3	Add 2TB	Dec., 2016
Rev 1.4	Add Encrypted Key/Authorized Key Management	Dec., 2016
Rev 2.0	Update TBW and test workload Mar., 2017	
Rev 2.1	Update 2TB performance June, 2017	
Rev 2.2	Update LBA with TCG OPAL function	July, 2017
Rev 2.3	Modify Quick erase function Aug.,2018	
Rev 2.4	Add TRIM Note Apr.,2019	
	Update RoHS report	
Rev 2.5	Remark TCG OPAL	Apr., 2023

List of Tables

9
9
0
0
1
1
1
3
8
8
9



List of Figures

FIGURE 1: INNODISK 2.5" SATA SSD 3MG2-P	. 7
FIGURE 2: INNODISK FID 2.5" SATA SSD 3MG2-P WITH AES BLOCK DIAGRAM	16
FIGURE 3: SIGNAL SEGMENT AND POWER SEGMENT	22
FIGURE 4: 2.5" SATA SSD 3MG2-P MECHANICAL SCREW HOLE	23

1. Product Overview

1.1 Introduction of Innodisk 2.5" SATA SSD 3MG2-P with AES function

Innodisk 2.5" SATA SSD 3MG2-P products provide high capacity flash memory Solid State Drive (SSD) that electrically complies with Serial ATA (SATA) standard. It supports SATA III standard (6.0GHz) with high performance. Innodisk 2.5" SATA SSD 3MG2-P is designed with AES engine, which is built-in the controller. When controller receives the data package from host, AES engine encrypts the data package and save the encrypted data into NAND flash. Thus, unauthorized personal has no access to decrypt the data in NAND flash. Innodisk 2.5" SATA SSD 3MG2-P supports several standard features, including TRIM, NCQ, and S.M.A.R.T and compliant with TCG OPAL 2.0 and IEEE 1667.

*TCG OPAL only support in 8GB~1TB.

CAUTION TRIM must be enabled.

TRIM enables SSD's controller to skip invalid data instead of moving. It can free up significant amount of resources, extends the lifespan of SSD by reducing erase, and write cycles on the SSD. Innodisk's handling of garbage collection along with TRIM command improves write performance on SSDs.

1.2 Product View and Models

Innodisk 2.5" SATA SSD 3MG2-P is available in follow capacities:

2.5" SATA SSD 3MG2-P 8GB 2.5" SATA SSD 3MG2-P 16GB 2.5" SATA SSD 3MG2-P 32GB 2.5" SATA SSD 3MG2-P 64GB 2.5" SATA SSD 3MG2-P 128GB 2.5" SATA SSD 3MG2-P 256GB 2.5" SATA SSD 3MG2-P 512GB 2.5" SATA SSD 3MG2-P 1TB 2.5" SATA SSD 3MG2-P 2TB



Figure 1: Innodisk 2.5" SATA SSD 3MG2-P



1.3 SATA Interface

Innodisk 2.5" SATA SSD 3MG2-P supports SATA III interface, and compliant with SATA I and SATA II. SATA III interface can work with Serial Attached SCSI (SAS) host system, which is used in server computer. Innodisk 2.5" SATA SSD 3MG2-P is compliant with Serial ATA Gen 1, Gen 2 and Gen 3 specification (Gen 3 supports 1.5Gbps /3.0Gbps/6.0Gbps data rate). SATA connector uses a 7-pin signal segment and a 15-pin power segment.

1.4 2.5-inch Form Factor

The Industry-standard 2.5-inch form factor design with metal material case is easy for installation, which has a compact design 69.85mm (W) $\times 100.00$ mm (L) $\times 6.90$ mm (H)

2. Product Specifications

2.1 Capacity and Device Parameters

2.5" SATA SSD 3MG2-P device parameters are shown in Table 1.

Capacity	LBA	Cylinders	Heads	Sectors	User Capacity(MB)
8GB	14900256	13587	16	63	7275
16GB	30367744	16383	16	63	14828
32GB	61300736	16383	16	63	29932
64GB	123166720	16383	16	63	60140
128GB	246898688	16383	16	63	120556
256GB	494362624	16383	16	63	241388
512GB	989290496	16383	16	63	483052
1TB	1979146240	16383	16	63	966380
2TB*	3958292478	16383	16	63	1932760

Table 1: Device parameters

* 2TB doesn't support TCG OPAL function

2.2 Performance

Burst Transfer Rate: 6.0Gbps

128GB 64GB 256GB 512GB 1TB Capacity Sequential* 520 MB/s 520 MB/s 520 MB/s 520 MB/s 520 MB/s Read (max.) Sequential 170 MB/s 320 MB/s 360 MB/s 360 MB/s 360 MB/s Write (max.) Micron 4KB Random 70,000 IOPS 70,000 IOPS 70,000 IOPS 70,000 IOPS 70,000 IOPS Read (QD32) 4KB Random 43,000 IOPS 64,000 IOPS 64,000 IOPS 64,000 IOPS 64,000 IOPS Write (QD32)

Table 2: Performance

Note: Performance based on CrystalDiskMark 3.03 with file size 1000M



	Capacity	8GB	16GB	16GB	32GB	32GB	64GB (4CH)	128GB	256GB	
		(1CH)	(1CH)	(2CH)	(2CH)	(4CH)	(400)	(4CH)	(4CH)	
	Sequential*	140 MB/s	140 MB/s	270 MB/s	270 MB/s	520 MB/s	520 MB/s	520 MB/s	520 MB/s	
	Read (max.)	110 110/5	110110/5	270110/5	270110/3	520 110/5	520 10/5	520 10/5	520 10/5	
Toshiba	Sequential	25 MD /-	25 MD/-	45 MD/-	45 MD/-	00 MD /-	00 MB /-	100 MD/-	250 MD/-	
15nm	Write (max.)	25 MB/s	25 MB/S	25 MB/s	45 MB/s	45 MB/s	90 MB/s	90 MB/s	180 MB/s	350 MB/s
(Slim	4KB Random	14,000	14,000	27,000	27,000	52,000	52,000	75,000	75,000	
inside)	Read (QD32)	IOPS	IOPS	IOPS	IOPS	IOPS	IOPS	IOPS	IOPS	
	4KB Random	6400	6400	11,500	11,500	23,000	23,000	46,000	83,000	
	Write (QD32)	IOPS	IOPS	IOPS	IOPS	IOPS	IOPS	IOPS	IOPS	

	Capacity	64GB (4CH)	128GB (4CH)	512GB (4CH)	1ТВ (4CH)	2TB (4CH)
	Sequential* Read (max.)	520 MB/s	520 MB/s	520 MB/s	520 MB/s	440 MB/s
Toshiba 15nm	Sequential Write (max.)	180 MB/s	300 MB/s	360 MB/s	360 MB/s	350 MB/s
(Full PCBA)	4KB Random Read (QD32)	75,000 IOPS	75,000 IOPS	75,000 IOPS	75,000 IOPS	12,000 IOPS
	4KB Random Write (QD32)	46,000 IOPS	80,000 IOPS	76,000 IOPS	78,000 IOPS	15,600 IOPS

Note: Performance based on CrystalDiskMark 3.03 with file size 1000M

2.3 Electrical Specifications

2.3.1 Power Requirement

Table 3: Innodisk 2.5" SATA SSD 3MG2-P Power Requirement

Item	Symbol	Rating	Unit
Input voltage	V_{IN}	+5 DC +- 5%	V

2.3.2 Power Consumption

	•
Mode	Power Consumption
Read	122 mA (max.)
Write	429 mA (max.)
Idle	84 mA (max.)
DEVSLP Mode	3mW (min.)
Slumber Mode	30mW (min.)

Table 4: Power Consumption

* Target: 2.5" SATA SSD 3MG2-P 256GB



Mode	Power Consumption				
Read	708 mA (max.)				
Write	1155 mA (max.)				
Idle	374 mA (max.)				

* Target: 2.5" SATA SSD 3MG2-P 2TB

2.4 Environmental Specifications

2.4.1 Temperature Ranges

Table 5: Temperature range for 2.5" SATA SSD 3MG2-P

Temperature	Range
Operating	Standard Grade: 0°C to +70°C
Operating	Industrial Grade:-40°C to +85°C
Storage	-55°C to +95°C

2.4.2 Humidity

Relative Humidity: 10-95%, non-condensing

2.4.3 Shock and Vibration

Table 6: Shock/Vibration Testing for 2.5" SATA SSD 3MG2-P

Reliability	Test Conditions	Reference Standards		
Vibration	7 Hz to 2K Hz, 20G, 3 axes	IEC 68-2-6		
Mechanical Shock	Duration: 0.5ms, 1500 G, 3 axes	IEC 68-2-27		

2.4.4 Mean Time between Failures (MTBF)

Table 7 summarizes the MTBF prediction results for various 2.5" SATA SSD 3MG2-P configurations. The analysis was performed using a RAM Commander[™] failure rate prediction.

- **Failure Rate**: The total number of failures within an item population, divided by the total number of life units expended by that population, during a particular measurement interval under stated condition.
- **Mean Time between Failures (MTBF)**: A basic measure of reliability for repairable items: The mean number of life units during which all parts of the item perform within their specified limits, during a particular measurement interval under stated conditions.

Product	Condition	MTBF (Hours)					
Innodisk 2.5" SATA SSD 3MG2-P	Telcordia SR-332 GB, 25°C	>3,000,000					

Table 7: 2.5" SATA SSD 3MG2-P MTBF

2.5 CE and FCC Compatibility

2.5" SATA SSD 3MG2-P conforms to CE and FCC requirements.

2.6 RoHS Compliance

2.5" SATA SSD 3MG2-P is fully compliant with RoHS directive.

2.7 Reliability

Parameter	Value			
Read Cycles	Unlimited Read Cycles			
Flash endurance	3,000 P/E cycles			
Wear-Leveling Algorithm	Support			
Bad Blocks Management	Support			
Error Correct Code	Support			
TBW* (Total Bytes Wri	tten) Unit:TB			
Capacity	Sequential workload	Client workload		
08GB	21.3	9.4		
16GB	42.6	18.8		
32GB	85.2	37.5		
64GB	170.5	75		
128GB	340.9	150		
256GB	681.8	300		
512GB	1364	600		
1TB	2663	1172		
2ТВ	5327	2344		
*NI-+				

*Note:

1. Sequential: Mainly sequential write, tested by Vdbench.

2. Client: Follow JESD218 Test method and JESD219A Workload, tested by ULINK. (The capacity lower

than 64GB client workload is not specified in JEDEC219A, the values are estimated.)

3. Based on out-of-box performance.

2.8 Transfer Mode

2.5" SATA SSD 3MG2-P support following transfer mode:

Serial ATA III 6.0Gbps

Serial ATA II 3.0Gbps

Serial ATA I 1.5Gbps

2.9 Pin Assignment

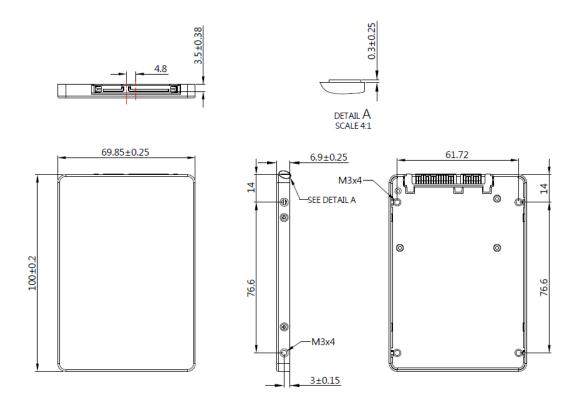
Innodisk 2.5" SATA SSD 3MG2-P uses a standard SATA pin-out. See Table 8 for 2.5" SATA SSD 3MG2-P pin assignment.

Table 8: Innodisk 2.5" SATA SSD 3MG2-P Pin Assignment

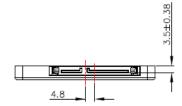
Name	Туре	Description				
S1	GND	NA				
S2	A+	Differential Cianal Dair A				
S3	A-	Differential Signal Pair A				
S4	GND	NA				
S5	B-					
S6	B+	Differential Signal Pair B				
S7	GND	NA				
Key and	d Spacing se	eparate signal and power segments				
P1	NC	NA				
P2	NC	NA				
Р3	NC	NA				
P4	GND	NA				
Р5	GND	NA				
P6	GND	NA				
P7	V5	5V Power, Pre-Charge				
P8	V5	5V Power				
Р9	V5	5V Power				
P10	GND	NA				
P11	DAS/DSS	Device Activity Signal / Disable Staggered				
P12	GND	NA				
P13	NC	NA				
P14	NC	NA				
P15	NC	NA				

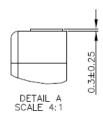
2.10 Mechanical Dimensions

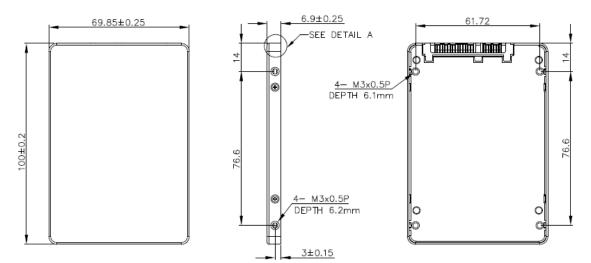
* DGS25-XXXD82BX3XX



* DGS25-XXXD82BX1XX/* DGS25-XXXD82BXAXX

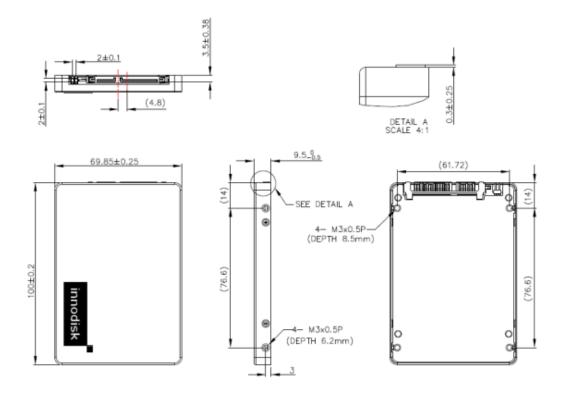






* DGS25-02TD82SXAXN/* DGS25-02TD82BXAXC

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2.11 Assembly Weight

An Innodisk 2.5" SATA SSD 3MG2-P within MLC flash ICs, 2TB's weight is 90 grams approx.

2.12 Seek Time

Innodisk 2.5" SATA SSD 3MG2-P is not a magnetic rotating design. There is no seek or rotational latency required.

2.13 Hot Plug

The SSD support hot plug function and can be removed or plugged-in during operation. User has to avoid hot plugging the SSD which is configured as boot device and installed operation system.

Surprise hot plug : The insertion of a SATA device into a backplane (combine signal and power) that has power present. The device powers up and initiates an OOB sequence.

Surprise hot removal: The removal of a SATA device from a powered backplane, without first being placed in a quiescent state.

2.14 NAND Flash Memory

Innodisk 2.5" SATA SSD 3MG2-P uses Multi Level Cell (MLC) NAND flash memory, which is non-volatility, high reliability and high speed memory storage.



3. Theory of Operation

3.1 Overview

Figure 2 shows the operation of Innodisk 2.5" SATA SSD 3MG2-P from the system level, including the major hardware blocks.

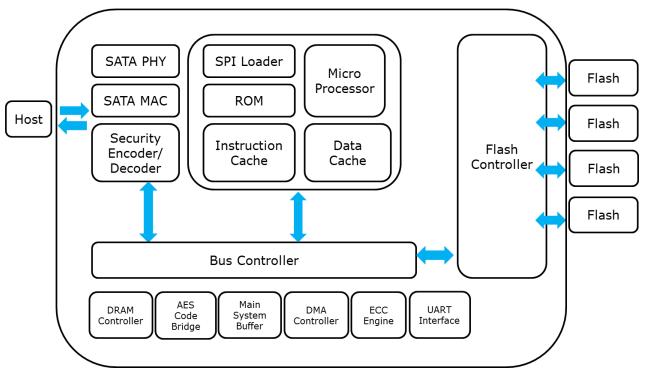


Figure 2: Innodisk 2.5" SATA SSD 3MG2-P with AES Block Diagram

Innodisk 2.5" SATA SSD 3MG2-P integrates a SATA III controller and NAND flash memories. Communication with the host occurs through the host interface, using the standard ATA protocol. Communication with the flash device(s) occurs through the flash interface. The AES engine was built-in the ID201 controller. When 2.5" SATA SSD 3MG2-P is initiated with Firmware, AES engine will generate a random number to be an AES key. Each SSD has a unique AES key when it leaves the factory.

* iCell is optional feature with different part number.

3.2 SATA III Controller

Innodisk 2.5" SATA SSD 3MG2-P is designed with ID 201 built-in 256bits AES engine, a SATA III 6.0Gbps (Gen. 3) controller, which supports external DDR3 DRAM. The Serial ATA physical, link and transport layers are compliant with Serial ATA Gen 1, Gen 2 and Gen 3 specification (Gen 3 supports 1.5Gbps/3.0Gbps/6.0Gbps data rate). The controller has 4 channels for flash interface.

3.3 Error Detection and Correction

Highly sophisticated Error Correction Code algorithms are implemented. The ECC unit consists of the Parity Unit (parity-byte generation) and the Syndrome Unit (syndrome-byte computation). This unit implements an algorithm that can correct 66 bits per 1024 bytes in an ECC block. Code-byte generation during write operations, as well as error detection during read operation, is implemented on the fly without any speed penalties.

3.4 Wear-Leveling

Flash memory can be erased within a limited number of times. This number is called the **erase cycle limit** or **write endurance limit** and is defined by the flash array vendor. The erase cycle limit applies to each individual erase block in the flash device.

Innodisk 2.5" SATA SSD 3MG2-P uses a static wear-leveling algorithm to ensure that consecutive writes of a specific sector are not written physically to the same page/block in the flash. This spreads flash media usage evenly across all pages, thereby extending flash lifetime.

3.5 Bad Blocks Management

Bad Blocks are blocks that contain one or more invalid bits whose reliability are not guaranteed. The Bad Blocks may be presented while the SSD is shipped, or may develop during the life time of the SSD. When the Bad Blocks is detected, it will be flagged, and not be used anymore. The SSD implement Bad Blocks management, Bad Blocks replacement, Error Correct Code to avoid data error occurred. The functions will be enabled automatically to transfer data from Bad Blocks to spare blocks, and correct error bit.

3.6 iData Guard

Innodisk's iData Guard is a comprehensive data protection mechanism that functions before and after a sudden power outage to SSD. Low-power detection terminates data writing before an abnormal power-off, while table-remapping after power-on deletes corrupt data and maintains data integrity. Innodisk's iData Guard provides effective power cycling management, preventing data stored in flash from degrading with use.

3.7 Garbage Collection/TRIM

Garbage collection and TRIM technology is used to maintain data consistency and perform continual data cleansing on SSDs. It runs as a background process, freeing up valuable controller resources while sorting good data into available blocks, and deleting bad blocks. It also significantly reduces write operations to the drive, thereby increasing the SSD's speed and lifespan.

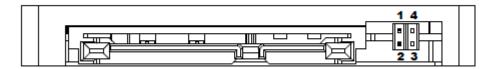


3.8 iCell Technology (Optional)

iCell circuit is designed with several capacitors to be able to provide power after host power off. The SSD controller can write all DRAM buffer data to flash, so that is why 2.5" SATA SSD 3MG2-P can ensure all data can be written to disk without any data loss.

3.9 Quick Erase (Optional)

QEraser function is designed for emergency data erase in few seconds by providing ATA command or shorting QEraser Pins (Pin 1 and Pin 2) with an external jumper to erase all of data block.



3.9.1 QEraser Command

- Protocol: No Data

-Inputs

Table 9: Execute Quick Erase command for inputs information

Register	7	6	5	4	3	2	1	0		
Features				21h						
Sector Count	41h									
LBA Low Na										
LBA Mid Na										
LBA High	Na									
Device	1 1 1 0 Na									
Command	82h									

-Normal Outputs

Table 10: Quick Erase command for normal output information

	7	6	5	4	3	2	1	0
Register		-						
Error Na								
Sector Count	r Count Na							
LBA Low	N Na							
LBA Mid Na								
LBA High Na								
Device	obs	Na	obs	DEV	Na	Na	Na	Na
Status	BSY	DRDY	DF	Na	DRQ	Na	Na	ERR



Device register-

DEV shall specify the selected device.

Status register

BSY will be cleared to zero indicating command completion

DRDY will be set to one.

DF (Device Fault) will be cleared to zero.

DRQ will be cleared to zero

ERR will be cleared to zero.

Table 11: Quick Erase time for Toshiba*

Capacity	Time
8GB	5 Sec.
16GB (1CH)	10 Sec.
16GB (2CH)	5 Sec.
32GB (2CH)	11 Sec.
32GB (4CH)	5 Sec.
64GB	6 Sec.
128GB	7 Sec.
256GB	13 Sec.
512GB	17 Sec.
1TB	34 Sec.

*Note: Based on Asrock H97M anniversary platform.

3.10 2.5" SATA SSD 3MG2-P AES function flow chart

In order to complete the physical security layer of protection, encryption needs to be paired with an ATA user password by ATA security command. After setting the authorized key by ATA security command, every time when you power on the system with SSD encrypted, you will be requested for a password to access the SSD. If the password is correct, the SSD will run well; if not, then you will not be able to access the SSD then.



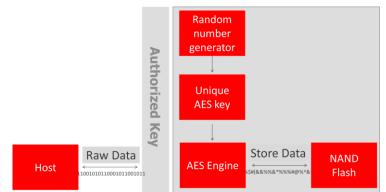


Figure 3: Innodisk 2.5" SATA SSD 3MG2-P AES flow chart

3.10.1 Encrypted Key Management

Innodisk 3MG2-P SSD includes two methods of key management to apply to different applications. The first is a standard approach that allows the firmware to generate a random number and a unique key when it leaves the factory. This method ensures that the user can easily apply the SSD with the data encrypted key. Another approach is to meet unique customer requirements with an encrypted key generated by an SSD from the SATA interface host. The SSD must keep the encrypted key value when receiving the reset commands. This method works best for the SSD as a removable device in different systems. Innodisk provides the test tool to execute the AES hardware encryption. This user-friendly tool, developed by Innodisk Corporation, allows the customer to use/test encryption functions.

3.10.2 Authorized Key Management

In order to complete the physical security layer of protection, encryption needs to be bundled with an ATA user password provided by an ATA Security command. Unlike the AES key, the authorized key must be set by the user via the BIOS configuration. Every time you power on the system with SSD encryption, a password request prompt is sent to access the SSD. If the password is correct, the SSD will run well; if not, you will not be able to access the SSD.

Command	Command Code
SECURITY SET PASSWORD	0XF1
SECURITY UNLOCK	0XF2
SECURITY ERASE PREPARE	0XF3
SECURITY ERASE UNIT	0XF4
SECURITY FREEZE LOCK	0XF5
SECURITY DISABLE PASSWORD	0XF6



3.10.3 TCG OPAL

OPAL is a set of specifications for features of data storage devices that enhance security. These specifications are published by the Trusted Computing Group's Storage Work Group. Innodisk 3MG2-P is compliant with TCG OPAL 2.0^(*1). The capability of TCG OPAL Security mode allows multiple users with independent access control to read/write/erase independent data areas (LBA ranges). Each locking range adjusts by authenticated authority. Note that by default there is a single "Global Range" that encompasses the whole user data area. In TCG Opal Security Mode, Revert, Revert SP and GenKey command can erase all of data including global range and locking range; in the meantime generate the new encrypted key.

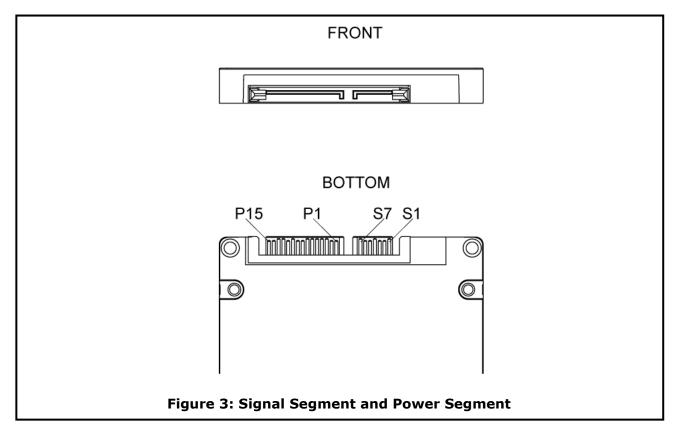
*1. You need to install TCG OPAL software to implement OPAL function, which is supplied by TCG OPAL software developed company

*2. 2TB doesn't support TCG OPAL



4. Installation Requirements

4.1 2.5" SATA SSD 3MG2-P Pin Directions



4.2 Electrical Connections for 2.5" SATA SSD 3MG2-P

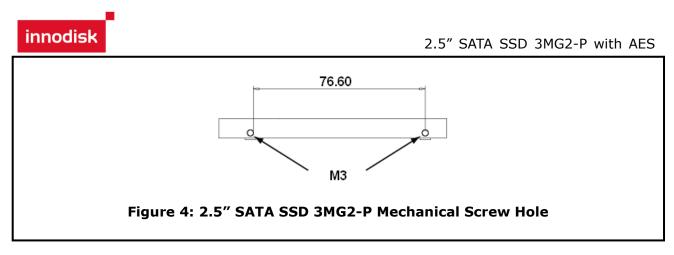
A Serial ATA device may be either directly connected to a host or connected to a host through a cable. For connection via cable, the cable should be no longer than 1meter. The SATA interface has a separate connector for the power supply. Please refer to the pin description for further details.

4.3 Form Factor

Please prepare following things:

- Screw driver.
- Four M3 screws. (Suggested torque value is 2.0~2.5 Kgf.cm)
- > SATA single cable (7-pin, Maximum length I meter).
- > SATA power cable (15-pin).

Please turn off your computer, and open your computer's case. Find one of available 2.5-inch slot, and plug the SSD in. To use the screws fix the SSD. Plug in the SATA single cable, and power cable. Please boot the installation Operation System from CD-ROM, and install Operation System into SSD.



4.4 Device Drive

No additional device drives are required. Innodisk 2.5" SATA SSD 3MG2-P can be configured as a boot device.

5. SMART Feature Set

Innodisk 3MG2-P series support the SMART command set and defines some vendor-specific data to report SMART attributes of SSD.

Value	Command
D0h	Read Data
D1h	Read Attribute Threshold
D2h	Enable/Disable Autosave
D3h	Save Attribute Values
D4h	Execute OFF-LINE Immediate
D5h	Read Log
D6h	Return Status
D8h	Enable SMART Operations
D9h	Disable SMART Operations
DAh	Return Status

5.1 SMART Attributes

Innodisk 3MG2-P series SMART data attributes are listed in following table.

Attribute ID (hex)	Raw Attribute Value							Attribute Name
1 (01h)	MSB	00	00	00	00	00	00	Raw Read Error Rate
5 (05h)	LSB	MSB	00	00	00	00	00	Reallocated Sector Count
9 (09h)	LSB			MSB	00	00	00	Power-on Hours
12 (0Ch)	LSB			MSB	00	00	00	Power Cycle Count
160 (A0h)	LSB			MSB	00	00	00	Uncorrectable sector count when read/write
161 (A1h)	LSB	MSB	00	00	00	00	00	Number of valid spare block
163 (A3h)	LSB	MSB	00	00	00	00	00	Number of initial invalid block
164 (A4h)	LSB	MSB	00	00	00	00	00	Total erase count
165 (A5h)	LSB			MSB	00	00	00	Maxumum erase count
166 (A6h)	LSB			MSB	00	00	00	Minimum erase count
167 (A7h)	LSB			MSB	00	00	00	Average erase count
168 (A8h)	LSB			MSB	00	00	00	Max erase count of spec
169 (A9h)	LSB			MSB	00	00	00	Reman Life (percentage)
175 (AFh)	LSB			MSB	00	00	00	Program fail count in worst die

inn	odisk							2.5" SATA SSD 3MG2-P with AES
176 (B0h)	LSB			MSB	00	00	00	Erase fail count in worst die
177 (B1h)	LSB			MSB	00	00	00	Total wear level count
178 (B2h)	LSB	MSB	00	00	00	00	00	Runtime invalid block count
181 (B5h)	LSB			MSB	00	00	00	Total program fail count
182 (B6h)	LSB	MSB	00	00	00	00	00	Total erase fail count
187 (BBh)	LSB			MSB	00	00	00	Uncorrectable error count
192 (C0h)	LSB	MSB	00	00	00	00	00	Power-Off Retract Count
194 (C2h)	MSB	00	00	00	00	00	00	Controlled temperature
195 (C3h)	LSB			MSB	00	00	00	Hardware ECC recovered
196 (C4h)	LSB			MSB	00	00	00	Reallocation event count
198 (C6h)	LSB			MSB	00	00	00	Uncorrectable error count off-line
199 (C7h)	LSB	MSB	00	00	00	00	00	UltraDMA CRC error count
225 (E1h)	LSB						MSB	Total LBAs written (each write unit = 32MB)
232 (E8h)	LSB	MSB	00	00	00	00	00	Available reserved space
241 (F1h)	LSB						MSB	Total LBAs written (each write unit = 32MB)
242 (F2h)	LSB						MSB	Total LBAs read (each write unit = 32MB)



6. AES Algorithm Certification

The following provides technical information about controller implementations that have been validated as confirming to the Advanced Encryption Standard (AES) Algorithm, Deterministic Random Bit Generator (DRBG) Algorithm, and Secure Hash Standard (SHS).

6.1 AES Algorithm

Val. No	Operational	Val. Date	Modes/States/Key sizes/Description/Notes
	Environment		
2474	Cadence	May/24/2013	Using the tests found in The Advanced Encryption
	NC-verilog		Standard Algorithm Validation Suite (AESAVS).
	hardware		This testing is performed by NVLAP accredited
	simulator v10.20		Cryptographic And Security Testing (CST)
			Laboratories.
			ECB (e/d; 128, 192, 256)
			XTS (KS: XTS_128)
			KS: XTS_256

6.2 DRBG Algorithm

Val. No	Operational	Val. Date	Modes/States/Key sizes/Description/Notes
	Environment		
337	Cadence	May/24/2013	Using the tests found in The DRBG Validation
	NC-verilog		Suite (DRBGVS). This testing is performed by
	hardware		NVLAP accredited Cryptographic And Security
	simulator v10.20		Testing (CST) Laboratories.
			HashBased DRBG:
			Prediction Resistance Tested: enabled and not
			enabled (SHA-256)

6.3 SHS Algorithm

Val. No	Operational	Val. Date	Modes/States/Key sizes/Description/Notes
	Environment		
2093	Cadence	May/24/2013	Has been validated as confirming to the Secure
	NC-verilog		Hash Algorithm specified in Federal Information
	hardware		Processing Standard (FIPS) 180-3, Secure Hash
	simulator v10.20		Standard (SHS), using tests described in the
			Secure Hash Algorithm Validation System

innodisk	2.5" SATA SSD 3MG2-P with AES
	(SHAVS). This testing is performed by NVLAP
	accredited Cryptographic And Security Testing
	(CST) Laboratories.
	SHA-256

7. Part Number Rule

	1	2	3	4	5	6	7	8	9	10	11	. 12		13	14	15	16	17	18	19	20	21
CODE	D				5	-		2						В	С	1	Q	С	(P)	-	x	x
Description	Disk			SAT. MG2			Ca	pacit	y	Cat	teg	jory	Flas	sh mode	Operation Temp.	Internal Control	CH.	Flash	icell			omized ode
												De	fin	ition								
		Co	de	1 st	(D	isl	k)							(Code 14	th (Ope	erati	ion Te	empe	ratı	ıre)	
D:Disk														C: Sta	ndard Gr	ade (0°	C~	+70 ℃)			
c	ode 2	nd ,	~ 5	th ((Fo	rn	ו Fa	act	or)				W: Ind	lustrial G	irade (-	40 °C	¢~ +8	5℃)			
GS25: 2.5′	′ SATA	SS	D 3	3MC	G2-I	Ρ																
	Code	2 7 ^t	^{:h} ~	9 tł	י (C	Cap	bac	ity)						Code	e 15 th (Int	ernal	cont	r ol)		
08G: 8GB														Compli	iant to 7	mm/9m	nm h	neight	housi	ng		
16G: 16GB	3																					
32G: 32GB	5													Code	16 th (Ch	annel	of d	ata ti	ransf	er)		
64G: 64GB	5													Q: Qua	ad Chanr	nels						
A28: 128G	В																					
B56: 256G	В																					
C12:512G	3																					
01T: 1TB															C	ode 17	th (F	lash	Туре)		
02T: 2TB														C: Tosl	hiba MLC	2						
	Code	e 10) th	~1	.2 th	(5	Ser	ies)													
D82: 2.5″	SATA S	SD	31	4G2	2-P	wi	th	AES	e	ngi	in	e										
C	ode 1	3 th	(Fi	irm	wa	re	ve	ersi	on)												
B: Synchror	nous Fla	ash	for	Tos	shiba	a 1	5nn	n								Code	18t	h (iC	ell)			
														P: iCel	l, reserv	ed for o	ptio	nal fu	nctior	1		
															Code 20	th ~21	th (C	Custo	mized	d co	de)	



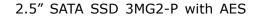
Appendix

innoc	ISK 宜鼎國際服	设份有限公司	司	Page 1
	Innodisk	Corporation	n	
		-	2) 7703-3555 Internet: http://	www.innodisk.
	RoHS 自我宣告書(R	oHS Declaration o	f Conformity)	
M	anufacturer Product: All In	nodisk EM Fla	ash and Dram	produc
	鼎國際股份有限公司(以下稱本公司) 1/65/EU及(EU) 2015/863 關於 RoHS =		司之所有產品,皆往	守合歐盟
Inn	nodisk Corporation declares that al ropean Union RoHS Directive (2011/	l products sold to		
、 本	公司同意因本保證書或與本保證書相關	事宜有所爭議時,	雙方宜友好協商,主	皇成協議。
	nodisk Corporation agrees that both in connection with this Declarati			
We of	公司聲明我們的產品符合 RoHS 指令的附 declare, our products permitted by the RoHS directive. (7a) Lead in high melting temperatu	the following exe	emptions specified	
We of ₩	declare, our products permitted by the RoHS directive.	the following exercise type solders(i.	emptions specified e. lead-based allo g lead in a glass or	oys contain ceramic ot
₩e of ፠	 declare, our products permitted by the RoHS directive. (7a) Lead in high melting temperature 85% by weight or more lead). (7C-I) Electrical and electronic common than dielectric ceramic in capacity 	the following exercise type solders(i.	emptions specified e. lead-based allo g lead in a glass or	oys contain ceramic ot
We of ※ ※	declare, our products permitted by the RoHS directive. (7a) Lead in high melting temperatur 85% by weight or more lead). (7C-I) Electrical and electronic com than dielectric ceramic in capacit or ceramic matrix compound.	the following exe re type solders(i. ponents containing ors, e.g. piezoel	emptions specified e. lead-based allo g lead in a glass or ectric devices, or	oys contain ceramic ot
We of ※ ※	declare, our products permitted by the RoHS directive. (7a) Lead in high melting temperatur 85% by weight or more lead). (7C-I) Electrical and electronic com than dielectric ceramic in capacit or ceramic matrix compound. Tame of hazardous substance	the following exercises the fo	emptions specified e. lead-based allo g lead in a glass or ectric devices, or	oys contain ceramic ot
We of ※ ※ N 契 汞	declare, our products permitted by the RoHS directive. (7a) Lead in high melting temperatur 85% by weight or more lead). (7C-I) Electrical and electronic com than dielectric ceramic in capacit or ceramic matrix compound. (ame of hazardous substance (Pb)	the following exercises the fo	emptions specified e. lead-based allo g lead in a glass or ectric devices, or	oys contain ceramic ot
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	We berefy confirm that the product/a) delivered to
	We hereby confirm that the product(s) delivered to
	Innodisk P/N Description All Innodisk EM FLASH Products
	contain(s) no hazardous substances or constituents exceeding the defined threshold 0.1 % by weight in homogenous material if not otherwise specified, as described in the candidate list table currently including 197 substances and shown on the ECHA
_	website (http://echa.europa.eu/de/candidate-list-table).
	contain(s) one or more hazardous substances or constituents exceeding 0.1 % by weight in homogenous material if not otherwise specified in candidate list table. Where the threshold value is exceeded, the substances in question are to be declared in accompanying <u>Appendix A</u> .
	Comply with REACH Annex XVII.
	Guarantor
Со	mpany name 公司名稱: <u>Innodisk Corporation 宜鼎國際股份有限公司</u>
Со	mpany Representative 公司代表人:Randy Chien 簡川勝
Со	mpany Representative Title 公司代表人職稱: <u>Chairman 董事長</u>



Certificate

Issue Date: August 19, 2014 Ref. Report No. ISL-14LE346CE : 2.5" SATA SSD 3MG2-P

Product Name Model(s) Brand Responsible Party Address

 D@S25-XXXD81*#%%&
 Innodisk
 rty : Innodisk Corporation
 SF.No.237, Sec. 1, Datong Rd., Xizhi Dist., New Taipei City 221, Taiwan (R.O.C.)

We, International Standards Laboratory, hereby certify that:

The device bearing the trade name and model specified above has been shown to comply with the applicable technical standards as indicated in the measurement report and was tested in accordance with the measurement procedures specified in European Council Directive- EMC Directive 2004/108/EC. The device was passed the test performed according to :

Standards:

EN 55022: 2010+AC2011 and CISPR 22: 2008 (modified) EN 61000-3-2: 2006+A1:2009 +A2:2009 and IEC 61000-3-2: 2005+A1:2008 +A2:2009 EN 61000-3-3: 2013 and IEC 61000-3-3: 2013 EN 55024: 2010 and CISPR 24: 2010 EN 61000-4-2: 2009 and IEC 61000-4-2: 2008 EN 61000-4-3: 2006+A1: 2008 +A2: 2010 and IEC 61000-4-3:2006+A1: 2007+A2: 2010 EN 61000-4-4: 2004 +A1:2010 and IEC 61000-4-4: 2004 +A1:2010

I attest to the accuracy of data and all measurements reported herein were performed by me or were made under my supervision and are correct to the best of my knowledge and belief. I assume full responsibility for the completeness of these measurements and vouch for the qualifications of all persons taking them.

International Standards Laboratory

No. 65, Gu Dai Keng Street, Hsi-Chih Dist.,

Tel: 886-2-2646-2550; Fax: 886-2-2646-4641

Hsi-Chih LAB:

(N) Nomko

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New Taipei City 221, Taiwan

Jim Chu Jim Chu / Director

Lung-Tan LAB: No. 120, Lane 180, San Ho Tsuen, Hsin Ho Rd., Lung-Tan Hsiang, Tao Yuan County 325, Taiwan Tel: 886-3-407-1718; Fax: 886-3407-1738



Certificate

Issue Date: August 19, 2014 ISL-14LE346FB Ref. Report No.

Product Name : 2.5" SATA SSD 3MG2-P Model(s) Brand Applicant Address

: D@S25-XXXD81*#%}#& : Innodisk : Innedisk Corporation : 5F.No.237, Sec. 1, Datong Rd., Xizhi Dist., New Taipei City 221, Taiwan (R.O.C.)

We, International Standards Laboratory, hereby certify that:

The device bearing the trade name and model specified above has been shown to comply with the applicable technical standards as indicated in the measurement report and was tested in accordance with the measurement procedures specified. (refer to Test Report if any modifications were made for compliance).

Standards:



FCC CFR. Title 47 Part 15 Subpart B: 2012- Section 15.107 and 15.109 ANSI C63.4-2009 Industry Canada Interference-Causing Equipment Standard ICES-003 Issue 5: 2012

Class B

I attest to the accuracy of data and all measurements reported herein were performed by me or were made under my supervision and are correct to the best of my knowledge and belief. I assume full responsibility for the completeness of these measurements and vouch for the qualifications of all persons taking them.

International Standards Laboratory

Jim Chu

im Chu / Director

Hsi-Chih LAB: No. 65, Gu Dai Kong Street, Hsi-Chih Dist., New Taipei City 221, Taiwan Tel: 886-2-2646-2550; Fax: 886-2-2646-4641



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